

**ABSTRACT**

One or more semiconductor manufacturing tools and a tool service layer are used to fulfill client requests, including manufacturing procedures and data collection steps, without referencing tool functions or tool service layer functions in the request. Initially, a service request is received from a client. Subsequently, one or more tool functions capable of being provided by the tools and one or more tool service layer functions capable of being provided by the tool service layer are identified. After these functions required for fulfilling the service request have been identified, the identified tool functions and tool service layer functions are performed, thereby fulfilling the client service request. Furthermore, in at least some embodiments, the service request need not specifically reference the substeps. Similarly, in at least some embodiments, the request does not reference the tool service layer functions required to fulfill the client request. In these situations, the required tool service layer functions are identified independently without information from the service request.